# 2.5V / 3.3V 1:10 Differential ECL/PECL/HSTL Clock Driver

#### Description

The MC100LVEP111 is a low skew 1–to–10 differential driver, designed with clock distribution in mind, accepting two clock sources into an input multiplexer. The PECL input signals can be either differential or single–ended (if the  $V_{BB}$  output is used). HSTL inputs can be used when the LVEP111 is operating under PECL conditions.

The LVEP111 specifically guarantees low output-to-output skew. Optimal design, layout, and processing minimize skew within a device and from device to device.

To ensure tightest skew, both sides of differential outputs identically terminate into  $50~\Omega$  even if only one output is being used. If an output pair is unused, both outputs may be left open (unterminated) without affecting skew.

The MC100LVEP111, as with most other ECL devices, can be operated from a positive  $V_{CC}$  supply in PECL mode. This allows the LVEP111 to be used for high performance clock distribution in +3.3 V or +2.5 V systems. Single–ended CLK input operation is limited to a  $V_{CC} \! \geq \! 3.0$  V in PECL mode, or  $V_{EE} \! \leq \! -3.0$  V in NECL mode. Designers can take advantage of the LVEP111's performance to distribute low skew clocks across the backplane or the board. In a PECL environment, series or Thevenin line terminations are typically used as they require no additional power supplies. For more information on using PECL, designers should refer to Application Note AN1406/D.

#### **Features**

- 85 ps Typical Device-to-Device Skew
- 20 ps Typical Output-to-Output Skew
- Jitter Less than 1 ps RMS
- Maximum Frequency > 3 Ghz Typical
- V<sub>BB</sub> Output
- 430 ps Typical Propagation Delay
- The 100 Series Contains Temperature Compensation
- PECL and HSTL Mode Operating Range:  $V_{CC}$  = 2.375 V to 3.8 V with  $V_{EE}$  = 0 V
- NECL Mode Operating Range: V<sub>CC</sub> = 0 V with V<sub>EE</sub> = -2.375 V to -3.8 V
- Open Input Default State
- LVDS Input Compatible

March, 2006 - Rev. 11

- Fully Compatible with MC100EP111
- Pb-Free Packages are Available\*



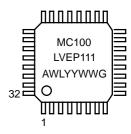
# ON Semiconductor®

http://onsemi.com

### MARKING DIAGRAM\*



LQFP-32 FA SUFFIX CASE 873A





QFN32 MN SUFFIX CASE 488AM MC100 LVEP111 ALYWG

A = Assembly Location

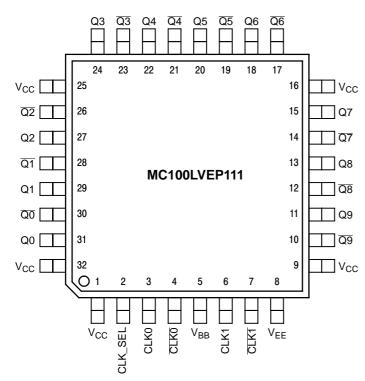
WL, L = Wafer Lot
 YY, Y = Year
 WW, W = Work Week
 G = Pb-Free Package

# ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

<sup>\*</sup>For additional marking information, refer to Application Note AND8002/D.



Warning: All  $V_{CC}$  and  $V_{EE}$  pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. LQFP-32 Pinout (Top View)

**Table 1. PIN DESCRIPTION** 

PIN	FUNCTION
CLK0*, <u>CLK0</u> **	ECL/PECL/HSTL CLK Input
CLK1*, CLK1**	ECL/PECL/HSTL CLK Input
Q0:9, <del>Q0:9</del>	ECL/PECL Outputs
CLK_SEL*	ECL/PECL Active Clock Select Input
V <sub>BB</sub>	Reference Voltage Output
V <sub>CC</sub>	Positive Supply
V <sub>EE</sub>	Negative Supply
EP	The exposed pad (EP) on the package
	bottom must be attached to a heat-sink-
	ing conduit. The exposed pad may only
	be electrically connected to $V_{\mbox{\scriptsize EE}}.$

<sup>\*</sup> Pins will default LOW when left open.

**Table 2. FUNCTION TABLE** 

CLK_SEL	Active Input
L	CLK0, <u>CLK0</u>
H	CLK1, <u>CLK1</u>

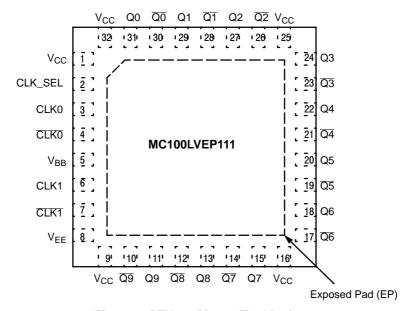


Figure 2. QFN-32 Pinout (Top View)

 $<sup>^{\</sup>star\star}\,$  Pins will default to  $V_{CC}\!/2$  when left open.

**Table 3. ATTRIBUTES** 

Characteri	stics	Value			
Internal Input Pulldown Resistor		75 kΩ			
Internal Input Pullup Resistor	37.5 kΩ				
ESD Protection	> 2 kV > 100 V > 2 kV				
Moisture Sensitivity (Note 1)		Pb Pkgs	Pb-Free Pkgs		
	LQFP QFN	Level 2 Level 1	Level 2 Level 1		
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in			
Transistor Count	602 Devices				
Meets or exceeds JEDEC Spec E	IA/JESD78 IC Latchup Test				

<sup>1.</sup> For additional information, refer to Application Note AND8003/D.

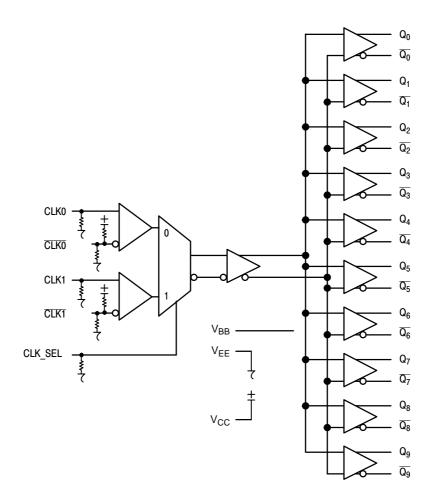


Figure 3. Logic Diagram

**Table 4. MAXIMUM RATINGS** 

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V <sub>CC</sub>	PECL Mode Power Supply	V <sub>EE</sub> = 0 V		6	V
V <sub>EE</sub>	NECL Mode Power Supply	V <sub>CC</sub> = 0 V		-6	V
VI	PECL Mode Input Voltage	V <sub>EE</sub> = 0 V	$V_{I} \leq V_{CC}$	6	V
	NECL Mode Input Voltage	V <sub>CC</sub> = 0 V	$V_I \ge V_{EE}$	-6	V
l <sub>out</sub>	Output Current	Continuous Surge		50 100	mA mA
I <sub>BB</sub>	V <sub>BB</sub> Sink/Source			± 0.5	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
θ <sub>JA</sub>	Thermal Resistance (Junction–to–Ambient)	0 lfpm 500 lfpm	LQFP-32 LQFP-32	80 55	°C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	LQFP-32	12 to 17	°C/W
$\theta_{JA}$	Thermal Resistance (Junction–to–Ambient)	0 lfpm 500 lfpm	QFN-32 QFN-32	31 27	°C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	2S2P	QFN-32	12	°C/W
T <sub>sol</sub>	Wave Solder Pb Pb–Free (QFN–32 Only)	< 3 sec @ 248°C < 3 sec @ 260°C		265 265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 5. PECL DC CHARACTERISTICS  $V_{CC} = 2.5 \text{ V}$ ;  $V_{EE} = 0 \text{ V}$  (Note 2)

			-40°C			25°C		85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I <sub>EE</sub>	Power Supply Current	60	90	120	60	90	120	60	90	120	mA
V <sub>OH</sub>	Output HIGH Voltage (Note 3)	1355	1480	1605	1355	1480	1605	1355	1480	1605	mV
V <sub>OL</sub>	Output LOW Voltage (Note 3)	555	730	900	555	730	900	555	730	900	mV
V <sub>IH</sub>	Input HIGH Voltage (Single–Ended) (Note 4)	1335		1620	1335		1620	1275		1620	mV
$V_{IL}$	Input LOW Voltage (Single–Ended) (Note 4)	555		875	555		875	555		875	mV
V <sub>IHCMR</sub>	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 5)	1.2		2.5	1.2		2.5	1.2		2.5	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μΑ
I <sub>IL</sub>	Input LOW Current CLK	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 2. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary + 0.125 V to -1.3 V.
- 3. All loading with 50  $\Omega$  to V<sub>EE</sub>.
- 4. Do not use  $V_{BB}$  at VCC < 3.0 V.
- 5. V<sub>IHCMR</sub> min varies 1:1 with V<sub>EE</sub>, V<sub>IHCMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>IHCMR</sub> range is referenced to the most positive side of the differential input signal.

Table 6. PECL DC CHARACTERISTICS  $V_{CC} = 3.3 \text{ V}$ ;  $V_{EE} = 0 \text{ V}$  (Note 6)

			-40°C 25°C		85°C						
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I <sub>EE</sub>	Power Supply Current	60	90	120	60	90	120	60	90	120	mA
V <sub>OH</sub>	Output HIGH Voltage (Note 7)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
V <sub>OL</sub>	Output LOW Voltage (Note 7)	1355	1530	1700	1355	1530	1700	1355	1530	1700	mV
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	2135		2420	2135		2420	2135		2420	mV
$V_{IL}$	Input LOW Voltage (Single-Ended)	1355		1675	1355		1675	1355		1675	mV
$V_{BB}$	Output Reference Voltage (Note 8)	1775	1875	1975	1775	1875	1975	1775	1875	1975	mV
V <sub>IHCMR</sub>	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 9)	1.2		3.3	1.2		3.3	1.2		3.3	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μΑ
I <sub>IL</sub>	Input LOW Current CLK	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 6. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary + 0.925 V to -0.5 V.
- 7. All loading with 50  $\Omega$  to  $V_{CC}$  2.0 V. 8. Single ended input operation is limited  $V_{CC} \ge 3.0$  V in PECL mode.
- 9. V<sub>IHCMR</sub> min varies 1:1 with V<sub>EE</sub>, V<sub>IHCMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>IHCMR</sub> range is referenced to the most positive side of the differential input signal.

Table 7. NECL DC CHARACTERISTICS  $V_{CC} = 0 \text{ V}$ ,  $V_{EE} = -2.375 \text{ V}$  to -3.8 V (Note 10)

		-40°C				25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I <sub>EE</sub>	Power Supply Current	60	90	120	60	90	120	60	90	120	mA
V <sub>OH</sub>	Output HIGH Voltage (Note 11)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
V <sub>OL</sub>	Output LOW Voltage (Note 11)	-1945	-1770	-1600	-1945	-1770	-1600	-1945	-1770	-1600	mV
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	-1165		-880	-1165		-880	-1165		-880	mV
$V_{IL}$	Input LOW Voltage (Single-Ended)	-1945		-1625	-1945		-1625	-1945		-1625	mV
$V_{BB}$	Output Reference Voltage (Note 12)	-1525	-1425	-1325	-1525	-1425	-1325	-1525	-1425	-1325	mV
V <sub>IHCMR</sub>	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 13)	V <sub>EE</sub>	+ 1.2	0.0	V <sub>EE</sub> ·	+ 1.2	0.0	V <sub>EE</sub> ·	+ 1.2	0.0	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μΑ
I <sub>IL</sub>	Input LOW Current CLK	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 10. Input and output parameters vary 1:1 with V<sub>CC</sub>.
- 11. All loading with 50  $\Omega$  to V<sub>CC</sub> 2.0 V.
- 12. Single ended input operation is limited  $V_{EE} \le -3.0V$  in NECL mode.
- 13. V<sub>IHCMR</sub> min varies 1:1 with V<sub>EE</sub>, V<sub>IHCMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>IHCMR</sub> range is referenced to the most positive side of the differential input signal.

Table 8. HSTL DC CHARACTERISTICS  $V_{CC} = 2.375$  to 3.8 V,  $V_{EE} = 0$  V

		-40°C		25°C			85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V <sub>IH</sub>	Input HIGH Voltage	1200			1200			1200			mV
$V_{IL}$	Input LOW Voltage			400			400			400	mV
Vx	Input Crossover Voltage	680		900	680		900	680		900	mV
I <sub>CC</sub>	Power Supply Current	70	100	120	70	100	120	70	100	120	mA

Table 9. AC CHARACTERISTICS  $V_{CC} = 0 \text{ V}$ ;  $V_{FF} = -2.375 \text{ to } -3.8 \text{ V}$  or  $V_{CC} = 2.375 \text{ to } 3.8 \text{ V}$ ;  $V_{FF} = 0 \text{ V}$  (Note 14)

			-40°C			25°C		85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f <sub>maxPECL/HSTL</sub>	Maximum Frequency (Figure 4)		3			3			3		GHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay (Differential Configuration)	325	400	475	350	430	500	440	510	590	ps
t <sub>skew</sub>	Within–Device Skew (Note 15) Within–Device Skew @ 2.5 V (Note 15) Device–to–Device Skew (Note 16)		20 20 85	25 25 150		20 20 85	25 25 150		25 20 85	35 25 150	ps
<sup>t</sup> JITTER	CLOCK Random Jitter (RMS) @ ≤3.0 GHz (Figure 4)		0.2	1		0.2	1		0.2	1	ps
V <sub>PP</sub>	Minimum Input Swing	150	800	1200	150	800	1200	150	800	1200	mV
t <sub>r</sub> /t <sub>f</sub>	Output Rise/Fall Time (20%–80%)	105	200	255	125	200	275	150	230	320	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 14. Measured with 750 mV source, 50% duty cycle clock source. All loading with 50  $\Omega$  to  $V_{CC}$  2.0 V.
- 15. Skew is measured between outputs under identical transitions and conditions on any one device.
- 16. Device–to–Device skew for identical transitions at identical  $V_{CC}$  levels.

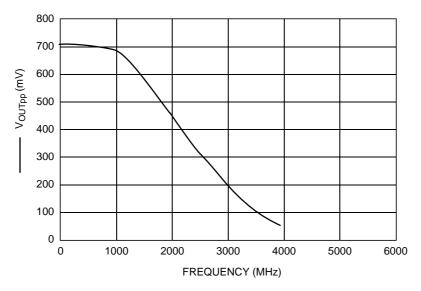


Figure 4. F<sub>max</sub> Typical

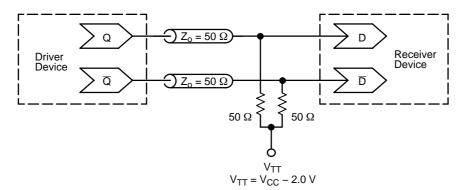


Figure 5. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC100LVEP111FA	LQFP-32	250 Units / Tray
MC100LVEP111FAG	LQFP-32 (Pb-Free)	250 Units / Tray
MC100LVEP111FAR2	LQFP-32	2000 / Tape & Reel
MC100LVEP111FARG	LQFP-32 (Pb-Free)	2000 Units / Tube
MC100LVEP111MNG	QFN-32 (Pb-Free)	74 Units / Tray
MC100LVEP111MNRG	QFN-32 (Pb-Free)	1000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **Resource Reference of Application Notes**

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1642/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

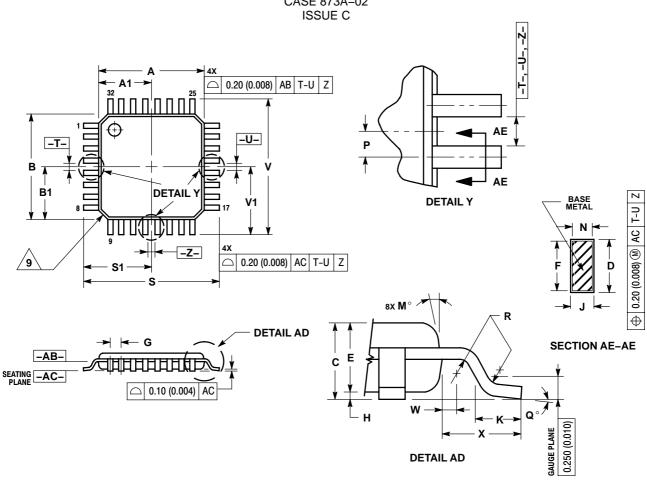
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

#### PACKAGE DIMENSIONS

# 32 LEAD LQFP CASE 873A-02



## NOTES:

- DIMENSIONING AND TOLERANCING
- PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION:
- MILLIMETER.

  3. DATUM PLANE –AB– IS LOCATED AT

- MILLIME TER.

  3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.

  4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.

  5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.

  6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.

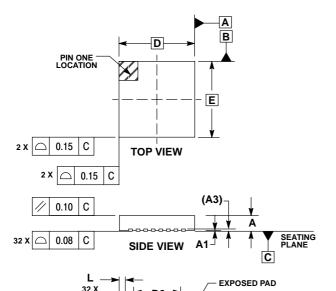
  7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.520 (0.020).

  8. MINIMUM SOLDER PLATE THICKNESS
- MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
- 9. EXACT SHAPE OF EACH CORNER MAY VARY FROM DEPICTION.

	MILLIN	IETERS	INC	HES			
DIM	MIN	MAX	MIN	MAX			
Α	7.000	BSC	0.276	BSC			
A1	3.500	BSC	0.138	BSC			
В	7.000	BSC	0.276 BSC				
B1	3.500	3.500 BSC		BSC			
С	1.400	1.600	0.055	0.063			
D	0.300	0.450	0.012	0.018			
Е	1.350	1.450	0.053	0.057			
F	0.300	0.400	0.012	0.016			
G	0.800	BSC	0.031 BSC				
Н	0.050	0.150	0.002	0.006			
ſ	0.090	0.200	0.004	0.008			
K	0.450	0.750	0.018	0.030			
M	12°	REF	12° REF				
N	0.090	0.160	0.004	0.006			
Р	0.400	BSC	0.016	BSC			
Q	1°	5°	1°	5°			
R	0.150	0.250	0.006	0.010			
S	9.000	BSC	0.354	BSC			
S1	4.500	BSC	0.177	BSC			
٧	9.000	BSC	0.354 BSC				
V1	4.500	BSC	0.177 BSC				
W	0.200	REF	0.008	REF			
Х	1.000	REF	0.039	REF			

#### PACKAGE DIMENSIONS

## QFN32 5\*5\*1 0.5 P CASE 488AM-01 ISSUE O

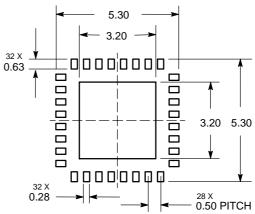


#### NOTES

- 1. DIMENSIONS AND TOLERANCING PER
- ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED
   TERMINAL AND IS MEASURED BETWEEN
   0.25 AND 0.30 MM TERMINAL
   COPLANARITY APPLIES TO THE EXPOSED
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MIL	LIMETE	ERS						
DIM	MIN	NOM	MAX						
Α	0.800	0.900	1.000						
A1	0.000	0.025	0.050						
A3	0.	0.200 REF							
b	0.180	0.300							
D	5	.00 BSC							
D2	2.950	3.100	3.250						
E	5	.00 BSC							
E2	2.950	3.100	3.250						
е	0.	500 BSC	)						
K	0.200								
Ĺ	0.300	0.400	0.500						

# **SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ECLinPS is a trademark of Semiconductor Components INdustries, LLC (SCILLC).

՝ ոոոո<sup>յ</sup>ոոփ փ

**BOTTOM VIEW** 

32

A B

0.10 C

32 X b

⊕ 0.05 C

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